TCA9617A 电平转换 FM+ I²C 总线中继器

1 特性

- 双通道双向 I²C 缓冲器
- 支持标准模式、快速模式 (400kHz) 和快速模式+ (1Mhz) I²C 操作
- 在 A 侧，工作电源电压范围为 0.8V 至 5.5V
- 在 B 侧，工作电源电压范围为 2.2V 至 5.5V
- 0.8V 至 5.5V 和 2.2V 至 5.5V 的电压电平转换
- 针对 TCA9517 的封装和功能替代产品
- 高电平有效中继器使能输入
- 漏极开路 I²C I/O
- 5.5V 电压容错 I²C 和启用输入支持
- 无闭锁操作
- 器件上支持时钟扩展和多控制器仲裁
- 闩锁性能超过 100mA，符合 JESD 78 II 类规范的要求
- ESD 保护性能超过 JESD 22 规范要求
  - 4000V 人体放电模型
  - 1500V 充电器件模型

2 应用

- 服务器
- 路由器（电信交换设备）
- 工业设备
- 包含多个 I²C 目标和/或长 PCB 布线的产品

3 说明

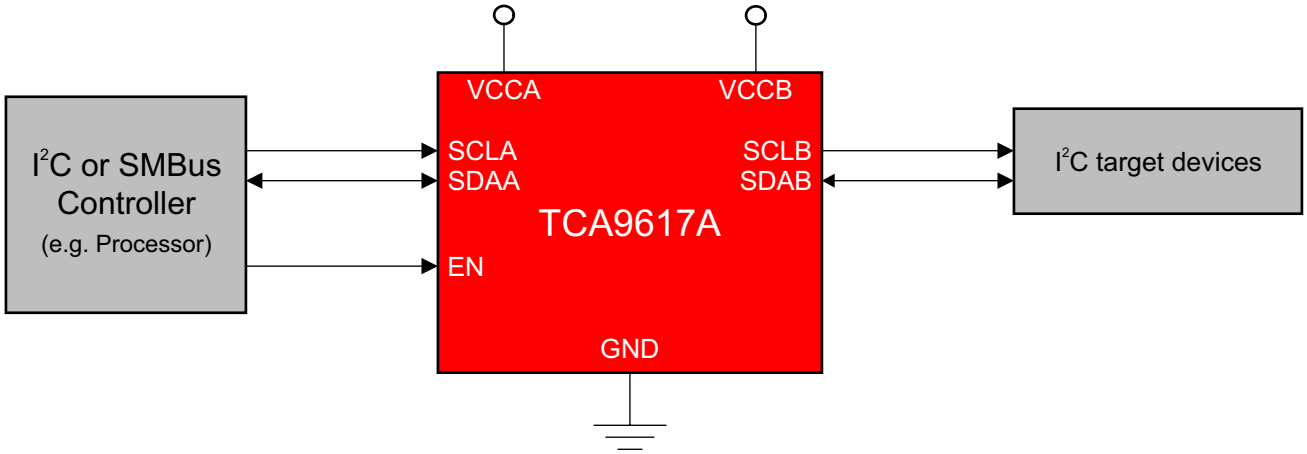
TCA9617A 是一款专门用于 I²C 总线和 SMBus 系统的 BiCMOS 双路双向缓冲器。此器件可在混合模式应用中提供低电压（低至 0.8V）和较高电压（2.2V 至 5.5V）间的双向电压电平转换（上行转换和下行转换）。电平转换期间，这个器件在不损失系统性能的情况下可扩展 I²C 和相似的总线系统。

TCA9617A 缓冲 I²C 总线上的串行数据 (SDA) 和串行时钟 (SCL) 信号，从而将两条 550pF 的总线连接至一个 I²C 应用。这款器件也可用于将总线隔离为电压和电容两部分。

封装信息

器件型号	封装(1)	封装尺寸(2)
TCA9617A	超薄小外形尺寸封装 (VSSOP) (8)	3mm × 3mm

(1) 有关更多信息，请参阅节 10。
(2) 封装尺寸（长 × 宽）为标称值，并包括引脚（如适用）。



简化版原理图

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4 Pin Configuration and Functions

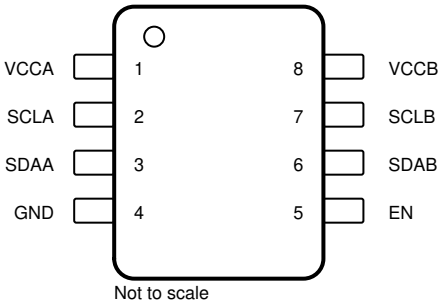


图 4-1. DGK Package, 8-Pin VSSOP (Top View)

表 4-1. Pin Functions

PIN		DESCRIPTION
NAME	NO.	
VCCA	1	A-side supply voltage (0.8V to 5.5V)
SCLA	2	I^2C SCL line, A side. Connect to V_{CCA} through a pull-up resistor.
SDAA	3	I^2C SDA line, A side. Connect to V_{CCA} through a pull-up resistor.
GND	4	Supply ground
EN	5	Active-high repeater enable input. Internally connected to V_{CCB} through a weak pull-up resistor.
SDAB	6	I^2C SDA line, B side. Connect to V_{CCB} through a pull-up resistor.
SCLB	7	I^2C SCL line, B side. Connect to V_{CCB} through a pull-up resistor.
VCCB	8	B-side and device supply voltage (2.2V to 5.5V)

5 Specifications

5.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
V_{CCB}	Supply voltage range		–0.5	6.5	V
V_{CCA}	Supply voltage range		–0.5	6.5	V
V_I	Enable input voltage range(2)		–0.5	6.5	V
V_{IO}	I^2C bus voltage range(2)		–0.5	6.5	V
I_{IK}	Input clamp current	$V_I < 0$		–50	mA
I_{OK}	Output clamp current	$V_O < 0$		–50	mA
I_O	Continuous output current			±50	mA
	Continuous current through V_{CC} or GND			±100	mA
T_{stg}	Storage temperature		–65	150	°C

(1) Operation outside the *Absolute Maximum Ratings* may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under *Recommended Operating Conditions*. If used outside the *Recommended Operating Conditions* but within the *Absolute Maximum Ratings*, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

5.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins(1)	±4000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins(2)	±1500	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CCA}	Supply voltage, A-side bus		0.8	V_{CCB}	V
V_{CCB}	Supply voltage, B-side bus		2.2	5.5	V
I_{OLA}	Low-level output current			30	mA
I_{OLB}	Low-level output current		0.1	30	mA
T_A	Ambient temperature		–40	85	°C

5.4 Thermal Information

THERMAL METRIC[1]		DGK	UNIT
		8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	171.5	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	77.5	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	107.1	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	12.3	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	105.3	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

5.5 Electrical Characteristics

V_{CCB} = 2.2V to 5.5V, GND = 0V, T_A = – 40°C to 85°C (unless otherwise noted)

PARAMETER			TEST CONDITIONS	V_{CCB}	MIN	TYP[1]	MAX	UNIT
V_{IK}	Input clamp voltage		I_I = -18mA	2.2V to 5.5V	-1.2		0	V
V_{OL}	Low-level output voltage	SDAB, SCLB	I_{OL} = 100µA or 30mA, V_{ILA} = 0V	2.2V to 5.5V	0.48	0.53	0.58	V
		SDAA, SCLA	I_{OL} = 30mA			0.1	0.23	
V_{IH}	High-level input voltage	SDAA, SCLA		2.2V to 5.5V	0.7 × V_{CCA}		5.5	V
		SDAB, SCLB			0.7 × V_{CCA}		5.5	
		EN			0.7 × V_{CCB}		5.5	
V_{IL}	Low-level input voltage	SDAA, SCLA		2.2V to 5.5V			0.3 × V_{CCA}	V
		SDAB, SCLB					0.4	
		EN					0.3 × V_{CCB}	
I_{CCA}	Quiescent supply current for V_{CCA}		Both channels low, SDAA = SCLA = GND and I_{OLB} =100µA, or SDAA = SCLA = open and SDAB = SCLB = GND	2.2V to 5.5V			13	µA
I_{CCB}	Quiescent supply current		Both Channels high, SDAA = SCLA = VCCA B-side pulled up to VCCB with pull-up resistors	2.2V to 5.5V		4.5	7	mA
			Both channels low, SDAA = SCLA = GND, I_{OLB} = 100µA	5.5V		5.7	8.1	

5.5 Electrical Characteristics（续）

V_{CCB} = 2.2V to 5.5V, GND = 0V, T_A = –40°C to 85°C (unless otherwise noted)

PARAMETER			TEST CONDITIONS	V_{CCB}	MIN	TYP(1)	MAX	UNIT
I_I	Input leakage current	SDAB, SCLB	V_I = V_{CCB}	2.2V to 5.5V	–1		1	μA
			V_I = 0.2V, EN = 0		–10		10	
			V_I = V_{CCB} – 0.2V		–1		1	
			V_I = 5.5V, V_{CCA} = 0V	0V	–10		10	
		SDAA, SCLA	V_I = V_{CCA}	2.2V to 5.5V	–1		1	
			V_I = 0.2V, EN = 0		–10		10	
			V_I = V_{CCA} – 0.2V		–1		1	
			V_I = 5.5V, V_{CCA} = 0V	0V	–10		10	
		EN	V_I = V_{CCB}		–1		1	
			V_I = 0.2V		–25			
C_I	Input capacitance	EN	V_I = 3V or 0V	3.3V			7	pF
C_{IO}	Input/output capacitance	SCLA, SDAA	V_I = 3V or 0V	3.3V			9	pF
				0V			9	
		SCLB, SDAB	V_I = 3V or 0V	3.3V			14	
				0V			14	

(1) All typical values are at T_A = 25°C.

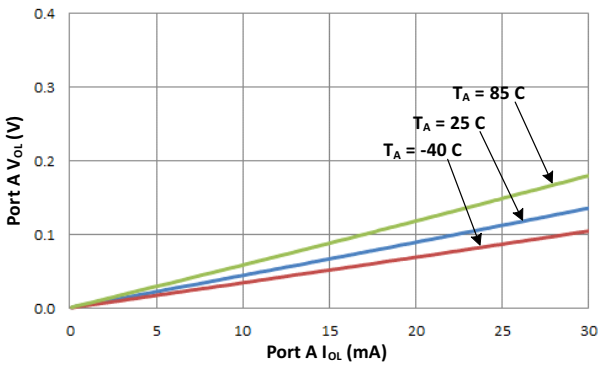
5.6 Timing Requirements

V_{CCA} = 0.8V to 5.5V, V_{CCB} = 2.2V to 5.5V, GND = 0V, TA = – 40°C to 85°C (unless otherwise noted)(1) (2) (3)

PARAMETER		FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay	SDAB, SCLB	SDAA, SCLA		35		90	ns
t_{PLH}	Propagation delay	SDAA, SCLA	SDAB, SCLB	$V_{CCB} \leqslant 3V$	50		137	ns
t_{PLH}	Propagation delay	SDAA, SCLA	SDAB, SCLB	$V_{CCB} > 3V$	59		250	ns
t_{PHL}	Propagation delay	SDAB, SCLB	SDAA, SCLA		32		144	ns
t_{PHL}	Propagation delay	SDAA, SCLA	SDAB, SCLB		28		140	ns
t_{TLH} (4)	Transition time	B side	30%	70%		88		ns
		A side				37		
t_{THL}	Transition time	B side	70%	30%	5.40		32	ns
		A side			1.40		40	
$t_{su,en}$ (5)	Setup time, EN high before Start condition				100			ns

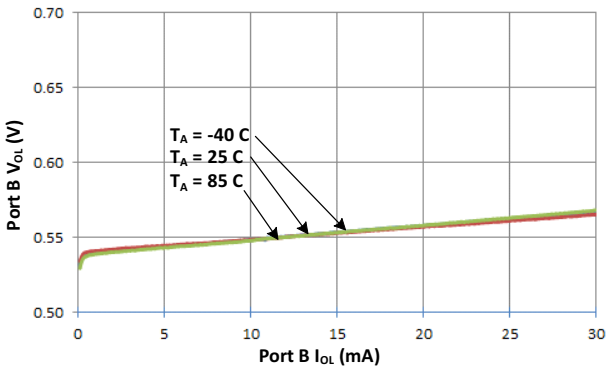
(1) Times are specified with loads of 240 Ω ±1% and 400 pF ±10% on B-side and 240 Ω ±1% and 200 pF ±10% on A-side. Different load resistance and capacitance alter the rise time, thereby changing the propagation delay and transition times.
(2) Times are specified with A-side signals pulled up to V_{CCA} and B-side signals pulled up to V_{CCB}.
(3) Typical values were measured with V_{CCA} = 0.9 V and V_{CCB} = 2.5 V at T_A = 25°C, unless otherwise noted.
(4) T_{TLH} is determined by the pull-up resistance and load capacitance
(5) EN should change state only when the global bus and the repeater port are in an idle state

5.7 Typical Characteristics



V_{CCA} = 0.9V V_{CCB} = 2.2V

图 5-1. Port A V_{OL} vs I_{OL}



V_{CCA} = 0.9V V_{CCB} = 2.2V

图 5-2. Port B $_{OL}$ vs I_{OL}

Parameter Measurement Information

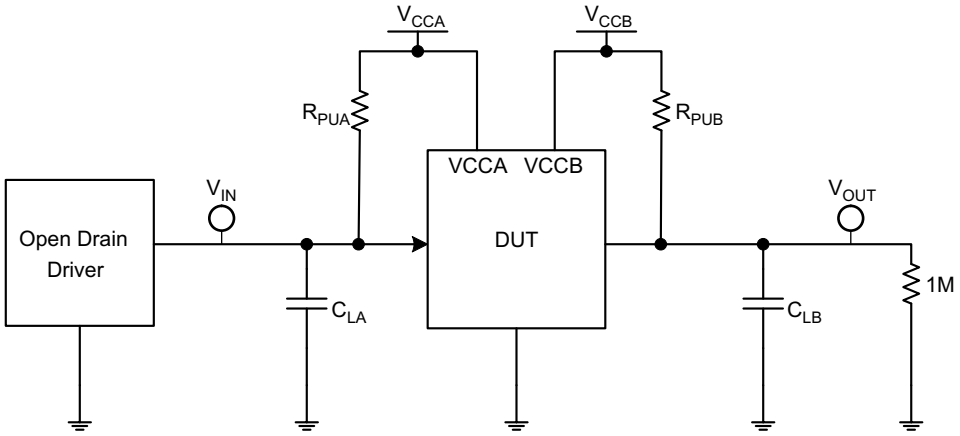
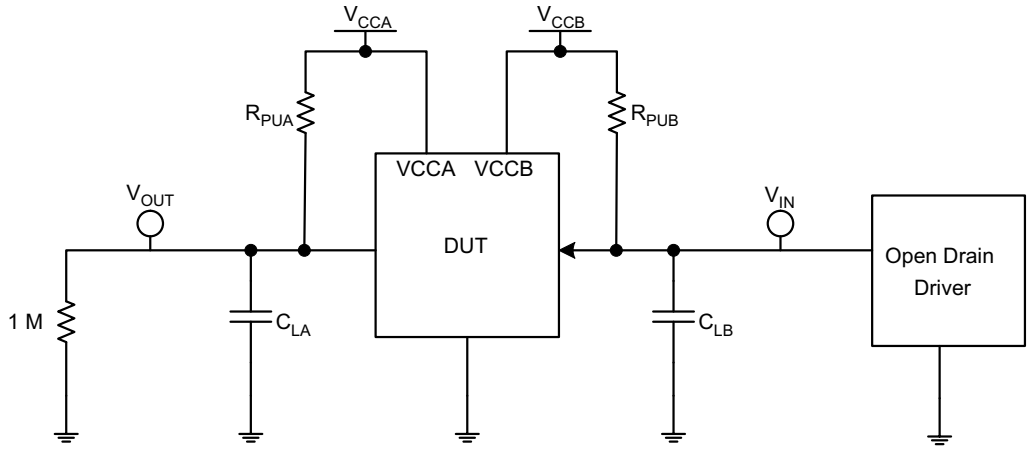


图 6-1. Test Circuit for Open-Drain Output from A to B



A. V_{CCA} = 0.9V
B. V_{CCB} = 2.5V
C. R_{PUA} = R_{PUB} = 240Ω on the A-side and the B-side
D. C_{LA} = 200pF on A-side and C_{LB} = 400pF on B-side (includes probe and jig capacitance)
E. All input pulses are supplied by generators having the following characteristics: PRR ⩽ 10MHz, Z_O = 50Ω, slew rate ⩾ 1V/ns
F. The outputs are measured one at a time, with one transition per measurement.

图 6-2. Test Circuit for Open-Drain Output from B to A

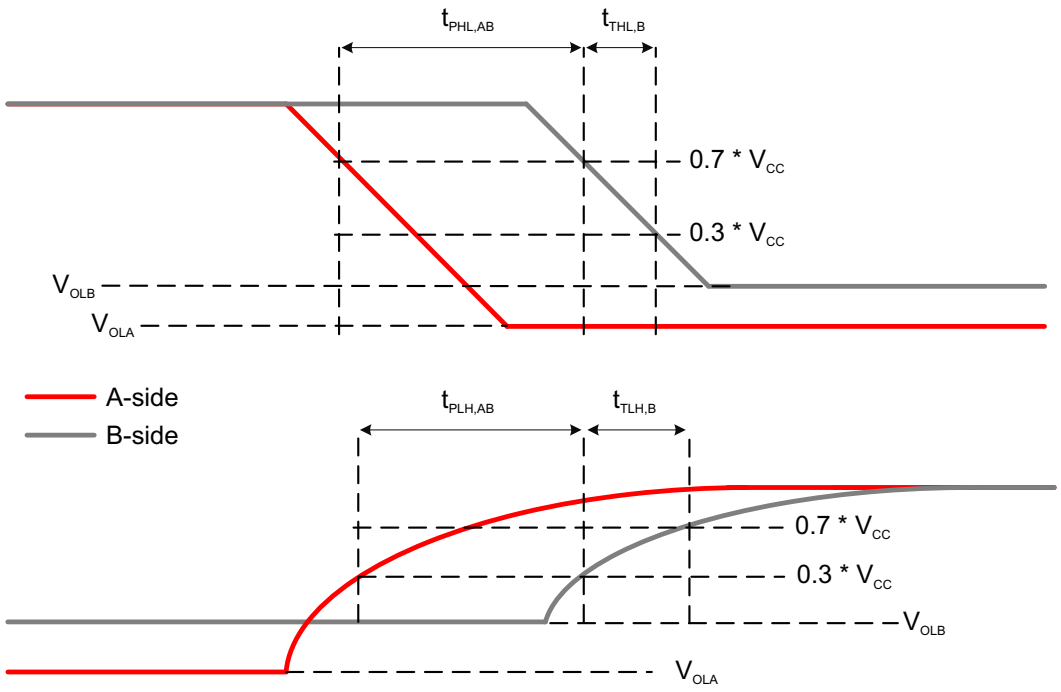


图 6-3. Propagation Delay And Transition Times (A to B)

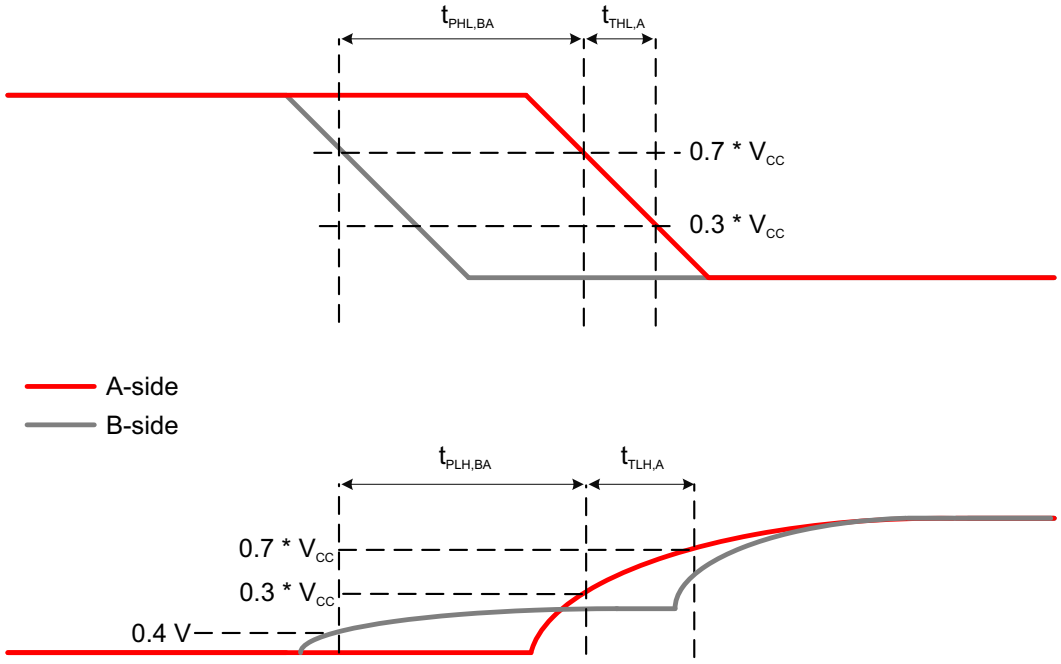


图 6-4. Propagation Delay And Transition Times (B to A)

6 Detailed Description

6.1 Overview

The TCA9617A is a BiCMOS dual bidirectional buffer intended for I^2C bus and SMBus systems. As with the standard I^2C system, pull-up resistors are required to provide the logic high levels on the buffered bus. The TCA9617A has standard open-drain configuration of the I^2C bus. The size of these pull-up resistors depends on the system, but each side of the repeater must have a pull-up resistor. The device is designed to work with Standard mode, Fast mode and Fast Mode+ I^2C devices.

The TCA9617A B-side drivers operate from 2.2V to 5.5V. The output low level for this internal buffer is approximately 0.5V, but the input voltage must be below V_{IL} when the output is externally driven low. The higher-voltage low signal is called a buffered low. When the B-side I/O is driven low internally, the low is not recognized as a low by the input. This feature prevents a lockup condition from occurring when the input low condition is released. This type of design on the B side prevents TCA9617A from being used in series with another TCA9617A B-side or other buffers that incorporate a static or dynamic offset voltage. This is because these devices do not recognize buffered low signals as a valid low and do not propagate the signal as a buffered low again.

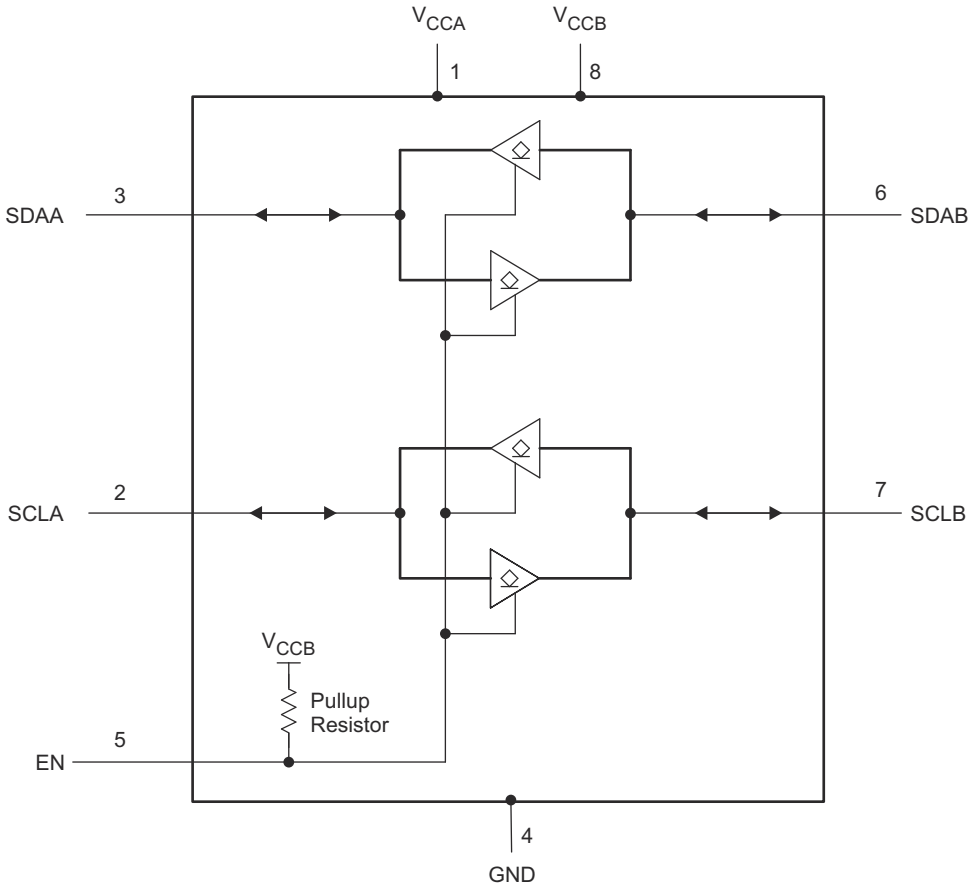
The TCA9617A A-side drivers operate from 0.8V to 5.5V and do not have the buffered low feature (or the static offset voltage). This means that a low signal on the B side translates to a nearly 0V low on the A side, which accommodates smaller voltage swings of low-voltage logic. The output pull-down on the A side drives a hard low, and the input level is set to 30% of V_{CCA} to accommodate the need for a lower low level in systems where the low-voltage-side supply voltage is as low as 0.8V.

The A side of two or more TCA9617As can be connected together to allow a star topology, with the A side on the common bus. Also, the A side can be connected directly to any other buffer with static or dynamic offset voltage. Multiple TCA9617As can be connected in series, A side to B side, with no buildup in offset voltage with only time-of-flight delays to consider.

The TCA9617A includes a power-up circuit that keeps the output drivers turned off until V_{CCB} is above 2V and V_{CCA} is above 0.7V. V_{CCA} is only used to provide references for the A-side input comparators and the power-good-detect circuit. The TCA9617A internal circuitry and all I/Os are powered by the V_{CCB} pin; however, due to ESD protection requirements on the SCLA and SDAA, V_{CCB} is required to power-up prior to V_{CCA}. IF SDA and SCL (on A-side or B-side) are pulled up to a positive voltage before V_{CCB} is powered, there can be significant current leakage into the SCA and SCL pins that can cause them to be pulled down. The SDA and SCL lines shall not be pulled up to a voltage higher than V_{CCB}, even when the device is powered down.

After power up and with the EN high, the A side falling below 30% of V_{CCA} turns on the corresponding B-side driver (either SDA or SCL) and drives the B-side down momentarily to 0V before settling to approximately 0.5V. When the A-side rises above 30% of V_{CCA}, the B-side pull-down driver is turned off and the external pull-up resistor pulls the pin high. If the B side falls first and goes below 0.4V, the A-side driver is turned on and drives the A-side to 0V. When the B-side rises above 0.45V, the A-side pull-down driver is turned off and the external pull-up resistor pulls the pin high.

6.2 Functional Block Diagram



6.3 Feature Description

6.3.1 Bidirectional Level Translation

The TCA9617A can provide bidirectional voltage level translation (up-translation and down-translation) between low voltages (down to 0.8V) and higher voltages (2.2V to 5.5V) in mixed-mode applications.

6.3.2 V_{OL} B-side Offset Voltage

图 6-2 depicts the offset voltage on the B side of the device. As shown in 图 6-2 the target releases and the B-side rises, and rises to 0.5V and stays there until the A-side rises above 30% of V_{CCA}. This effect can cause the low level signal to have a *pedestal*. Once the voltage on the A-side crosses 30% of V_{CCA}, the B-side begins to rise to V_{CCB}.

Due to nature of the B-side pedestal and the static offset voltage, there is a slight overshoot as the B-side rises from being externally driven low to the 0.5V offset. The TCA9617A is designed to control this behavior provided the system is designed with rise times greater than 20ns. Therefore, care must be taken to limit the pullup strength when devices with rise time accelerators are present on the B side. Excessive overshoot on the B-side pedestal can cause devices with rise time accelerators to trip prematurely if the accelerator thresholds are below 30% of V_{CCB}.

6.3.3 High to Low Transition Characteristics

When the A side of the bus is driven to 30% of V_{CCA}, the B side driver turns on. This drives the B-side to 0V for a short period (see 图 6-2) and then the B-side rises to the static offset voltage of 0.5V (V_{OL} of TCA9617A). This effect, called an inverted pedestal, allows the B-side to drive to logic low much faster than driving to the static offset. Driving to the static offset voltage requires that the fall time be slowed to prevent ringing.

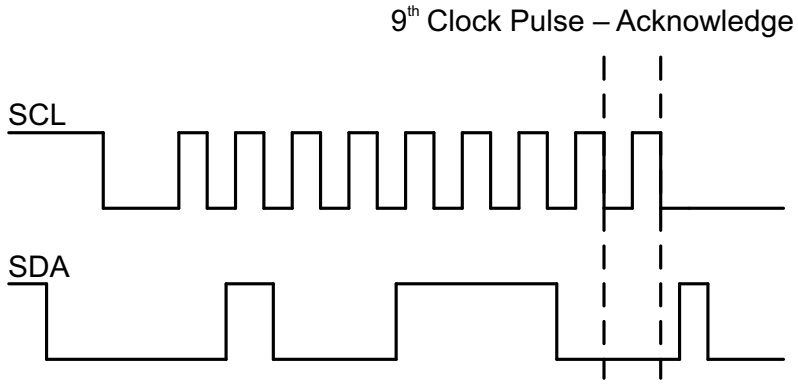


图 6-1. Bus A (0.8V to 5.5V Bus) Waveform

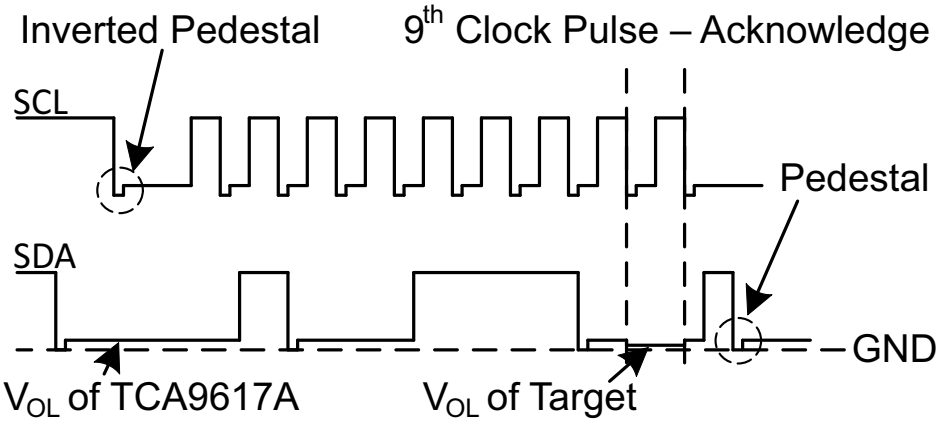


图 6-2. Bus B (2.2V to 5.5V Bus) Waveform

6.4 Device Functional Modes

The TCA9617A has an active-high enable (EN) input with an internal pull-up to V_{CCB}, which allows the user to select when the repeater is active. This can be used to separate a misbehaving target on power-up reset. The EN must never change state during an I^2C operation. Disabling during a bus operation can hang the bus. Enabling part way through the bus cycles can confuse the I^2C parts being enabled. The EN input must change state only when the global bus and repeater port are in the idle state to prevent system failures.

表 6-1. Function Table

INPUT EN	FUNCTION
L	Outputs disabled
H	SDAA = SDAB SCLA = SCLB

7 Application and Implementation

备注

以下应用部分中的信息不属于 TI 器件规格的范围，TI 不担保其准确性和完整性。TI 的客 户应负责确定器件是否适用于其应用。客户应验证并测试其设计，以确保系统功能。

7.1 Application Information

A typical application is shown in 图 7-1. In this example, the system controller is running on a 0.9V I^2C bus, and the target is connected to a 2.5V bus. Both buses are running at 400kHz. Decoupling capacitors are required but are not shown in 图 7-6 for simplicity.

The TCA9617A is 5V tolerant so no additional circuits are required to translate between 0.8V to 5.5V bus voltages and 2.7V to 5.5V bus voltages.

When the A side of the TCA9617A is pulled low by a driver on the I^2C bus, a comparator detects the falling edge when the signal level goes below 30% of V_{CCA} and cause the internal driver on the B side to turn on. The B-side is first pull down to 0V and then settle to 0.5V. When the B side of the TCA9617A falls below 0.4V, the TCA9617A detects the falling edge, turn on the internal driver on the A side and pull the A-side pin down to ground. To illustrate what can be seen for an A to B transition refer to 图 7-3, and for a B to A transition see 图 7-2.

On the B-side bus of the TCA9617A, the clock and data lines have a positive offset from ground equal to the V_{OL} of the TCA9617A. After the eighth clock pulse, the data line is pulled to the V_{OL} of the target device, which is close to ground in this example. At the end of the acknowledge, the level rises only to the low level set by the driver of the TCA9617A for a short delay (approximately 0.5V), while the A-side bus rises above 30% of V_{CCA} and then continues high.

Although the TCA9617A has a single application, the device can exist in multiple configurations. 图 7-1 shows the standard configuration for the TCA9617A. Multiple TCA9617As can be connected either in star configuration (图 7-4) or in series configuration (图 7-5). The design requirements , detailed design procedure, and application curves in 节 7.2.1 are valid for all three configurations.

7.2 Typical Application

7.2.1 Standard Application

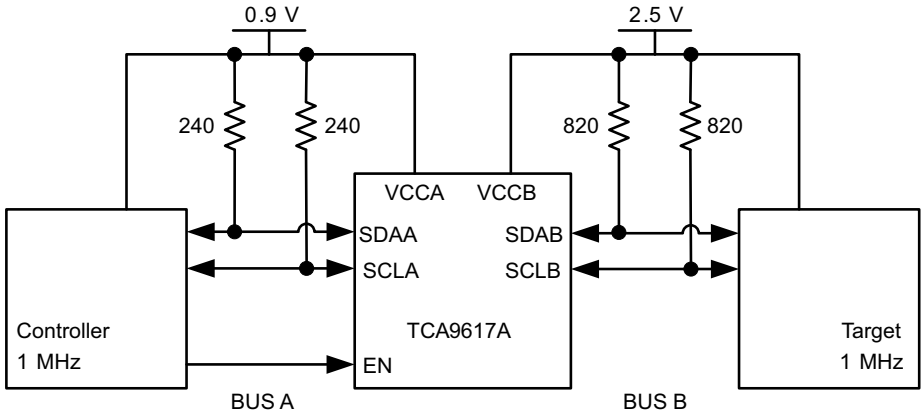


图 7-1. Bidirectional Voltage Level Translator

7.2.1.1 Design Requirements

For the level-translating application, the following must be true:

- V_{CCA} = 0.8V to 5.5V
- V_{CCB} = 2.2V to 5.5V
- $I_{OL} > I_O$

7.2.1.2 Detailed Design Procedure

7.2.1.2.1 Pullup Resistor Sizing

For the TCA9617A to function correctly, all devices on the B-side must be able to pull the B-side below the voltage input low contention level (0.4V). This means that the V_{OL} of any device on the B-side must be below 0.4V for proper operation.

The V_{OL} of a device can be adjusted by changing the I_{OL} through the device which is set by the pull-up resistor value. The pull-up resistor on the B-side must be carefully selected to make sure the logic levels is transferred correctly to the A-side.

The B-side pull-up resistor sizing must also make sure that the rise time is greater than 20ns. Shorter rise times increase the pedestal overshoot shown in 图 7-2.

7.2.1.3 Application Curves

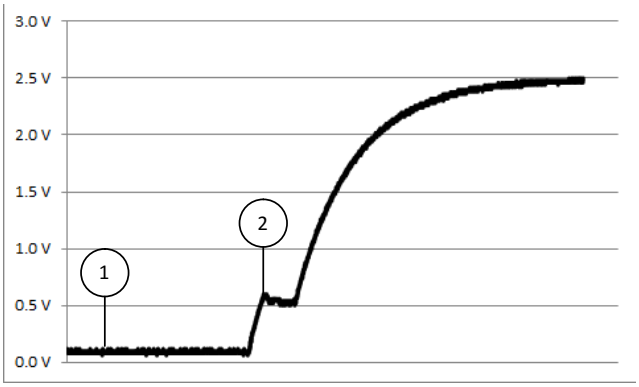


图 7-2. B-side Pedestal

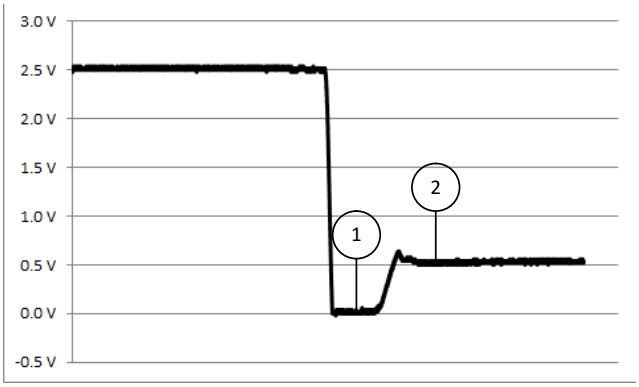


图 7-3. B-side Inverted Pedestal

7.2.2 Star Application

Multiple TCA9617A A sides can be connected in a star configuration, allowing all nodes to communicate with each other.

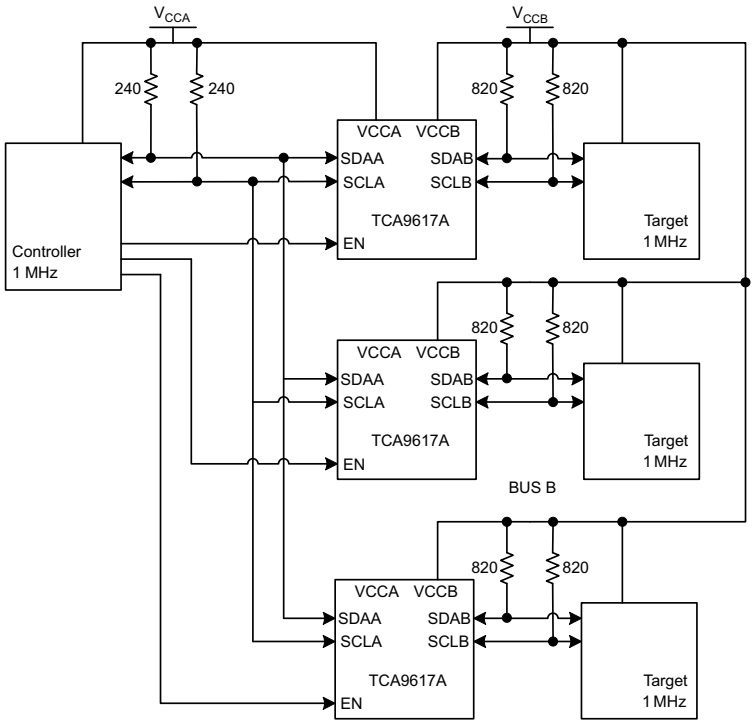


图 7-4. Typical Star Application

7.2.2.1 Design Requirements

Refer to *节 7.2.1.1*.

7.2.2.2 Detailed Design Procedure

Refer to *节 7.2.1.2*.

7.2.2.3 Application Curves

Refer to *节 7.2.1.3*.

7.2.3 Series Application

Multiple TCA9617As can be connected in series as long as the A side is connected to the B side. I²C bus target devices can be connected to any of the bus segments. The number of devices that can be connected in series is limited by repeater delay/time-of-flight considerations on the maximum bus speed requirements.

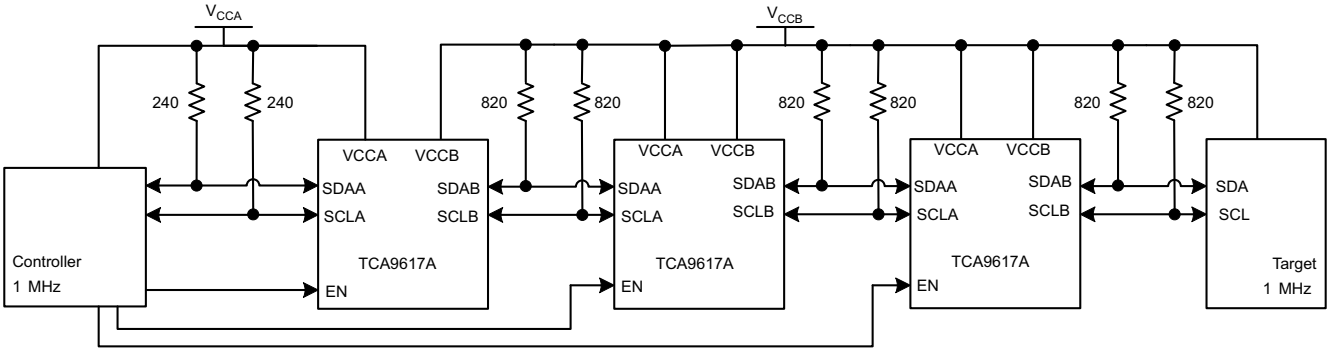


图 7-5. Typical Series Application

7.2.3.1 Design Requirements

Refer to 节 7.2.1.1.

7.2.3.2 Detailed Design Procedure

Refer to 节 7.2.1.2.

7.2.3.3 Application Curves

Refer to 节 7.2.1.3.

7.3 Power Supply Recommendations

For VCCA, an 0.8V to 5.5V power supply is required. For VCCB, a 2.2V to 5.5V power supply is required.

VCCB can always be higher than VCCA. VCCB cannot be lower than VCCA even when the device is disabled. During power-up, VCCB must rise before VCCA.

Standard decoupling capacitors are recommended. These capacitors typically range from 0.1μF to 1μF, but the value of the capacitance depends on the frequencies of noise from the power supply.

7.4 Layout

7.4.1 Layout Guidelines

The recommended decoupling capacitors must be placed as close to the VCCA and VCCB pins of the TCA9617A as possible.

7.4.2 Layout Example

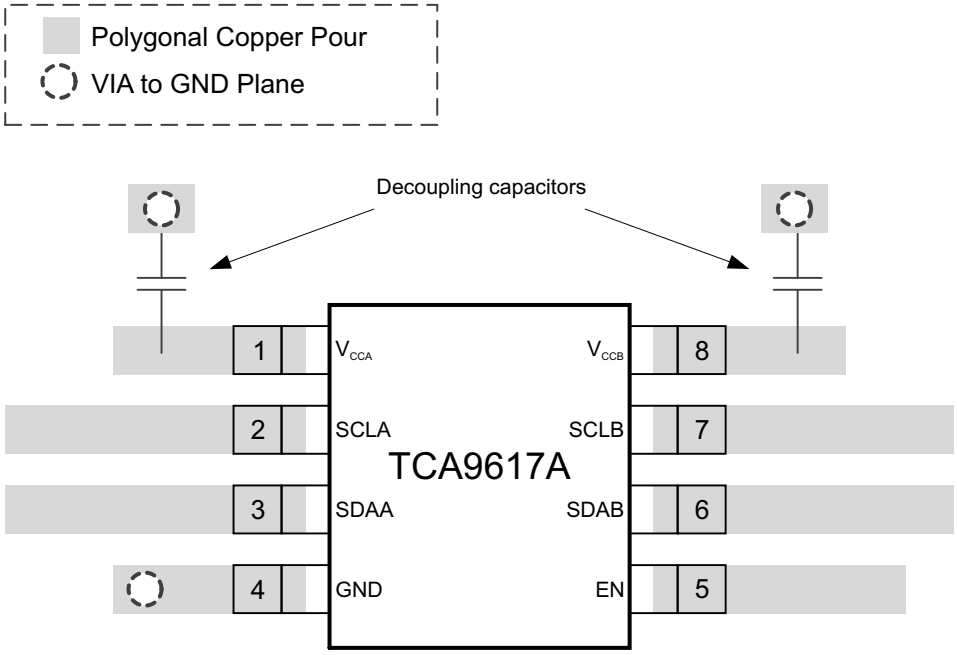


图 7-6. Layout Schematic

8 Device and Documentation Support

8.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert* me to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

8.2 支持资源

TI E2E™ 中文支持论坛是工程师的重要参考资料，可直接从专家处获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题，获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的使用条款。

8.3 Trademarks

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8.4 静电放电警告

静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

8.5 术语表

TI 术语表	本术语表列出并解释了术语、首字母缩略词和定义。

9 Revision History

Changes from Revision B (December 2018) to Revision C (January 2024) **Page**

- 将提到的旧术语实例全部更改为控制器和目标 1
- 将“器件信息”表更改为*封装信息*表 1
- 将*说明*中的*隔离*更改为*分离* 1
- 删除了“或更大的总线电容” 1
- Added internal pull-up resistor information on EN pin 3
- Changed abs max voltages from 7V to 6.5V 4
- Changed the Thermal Information for 8 DGK 5
- Changed V_{IK} MAX value of -1.2V to a MIN value 5
- Changed T_{PLH} (B to A) by removing typical value 7
- Changed T_{PLH} (A to B) for VCCB ⩽ 3V by changing min value from 59ns to 50ns and removing typical value 7
- Changed T_{PLH} (A to B) for VCCB > 3V by removing typical value 7
- Changed T_{PHL} (B to A) by changing min value from 69ns to 32ns and removing typical value 7
- Changed T_{PHL} (A to B) by changing min value from 68ns to 28ns and removing typical value 7
- Changed T_{THL} (B side) by changing max value from 13.8ns to 32ns and removing typical value 7
- Changed T_{THL} (B side) by changing max value from 11.3ns to 40ns and removing typical value 7
- Changed $0.3V_{CCA}$ to: *30% of V_{CCA}* in the *Overview* 10
- Changed A side falling below $0.7V_{CCA}$ to: *A side falling below 30% of V_{CCA}* 10
- Changed goes below $0.7V_{CCB}$ to: *goes below 0.4V* 10
- Changed "70mV or more below the output low level" to: *goes below V_{IL}* 10
- Changed $0.3V_{CCA}$ to: *30% of V_{CCA}* in the *Low to High Transition Characteristics* 11
- Changed "accelerator thresholds are below 30% of V_{CCB}" to: "overshoot is more than accelerator thresholds" 11
- Deleted *Since the A-side does not have a static offset low voltage, no pedestal is seen on the A-side as shown in Bus A (0.8V to 5.5V Bus) Waveform* 11
- Changed $0.7V_{CCA}$ to *30% of V_{CCA}* in the *High-to-Low Transition Characteristics* 12
- Changed *isolate a badly behaved* to *separate a misbehaving* in the *Device Functional Modes* 12
- Changed $0.7V_{CCA}$ to *30% of V_{CCA}* in the *Application Information* 13
- Changed falls below 0.45V to: *falls below 0.4V* 13
- Changed (0.45V) to: *(0.4V)* in the *Pullup Resistor Sizing* 14

Changes from Revision A (July 2014) to Revision B (December 2018) **Page**

- Changed the appearance of the DGK pin out image 3
- Deleted $V_{CCA} < V_{CCB}$ from the Design Requirements list 14

Changes from Revision * (June 2013) to Revision A (July 2014) **Page**

- 从“特性”列表中删除了“断电高阻抗 I^2C 引脚” 1
- 添加了“应用” 1
- Added Typical Characteristics section. 7
- Added Application and Implementation section. 13
- Added Power Supply Recommendations section. 16

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TCA9617ADGKR	Active	Production	VSSOP (DGK) | 8	2500 | LARGE T&R	Yes	NIPDAU | SN | NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	(7EA, DWK)
TCA9617ADGKR.A	Active	Production	VSSOP (DGK) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(7EA, DWK)
TCA9617ADGKR.B	Active	Production	VSSOP (DGK) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(7EA, DWK)

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

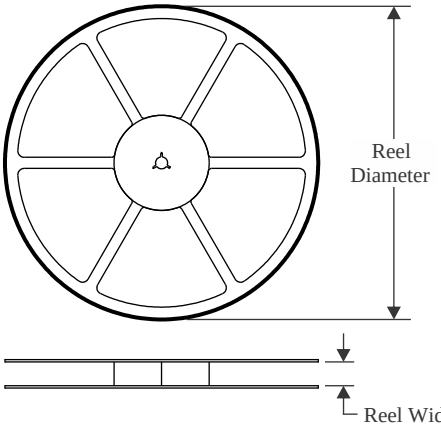
(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

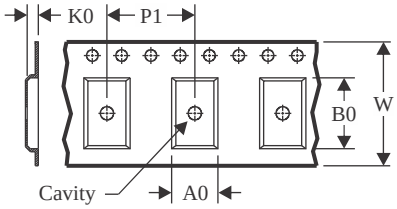
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

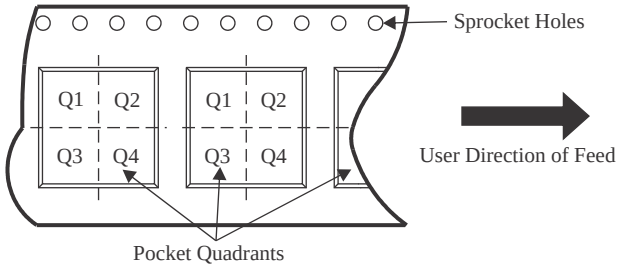


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

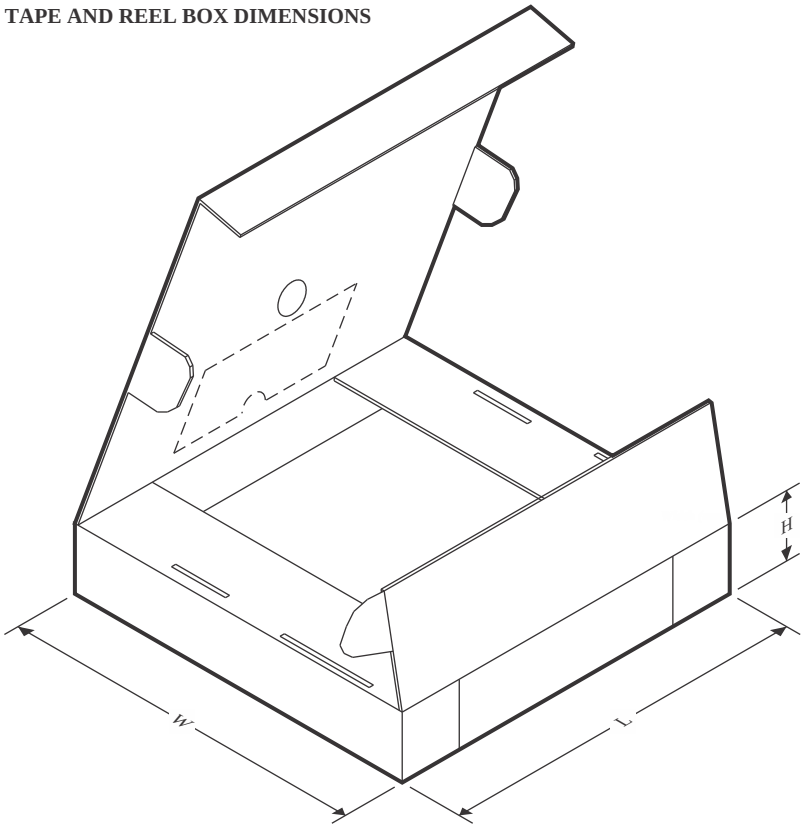
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TCA9617ADGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TCA9617ADGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

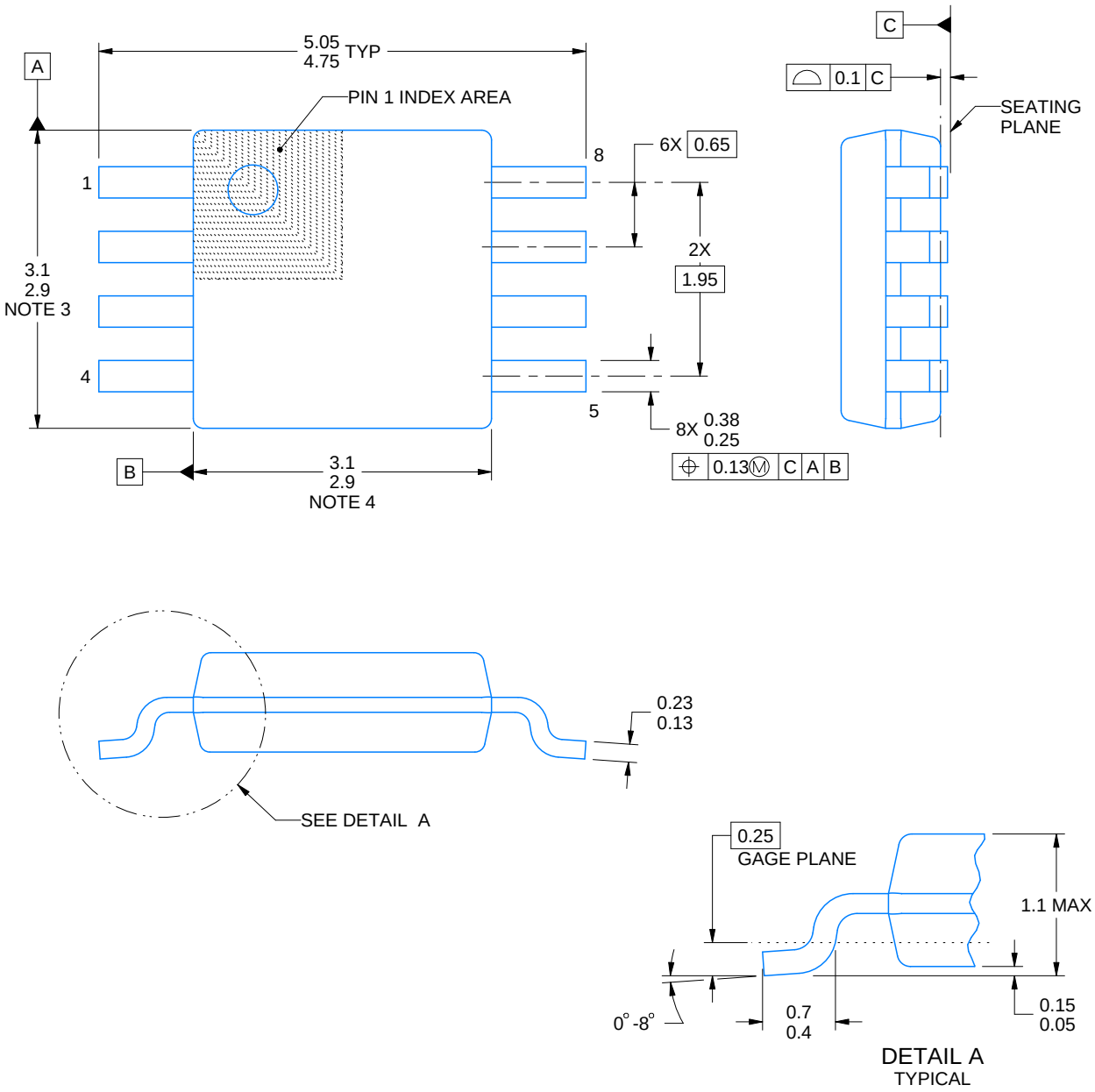
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TCA9617ADGKR	VSSOP	DGK	8	2500	353.0	353.0	32.0
TCA9617ADGKR	VSSOP	DGK	8	2500	353.0	353.0	32.0

PACKAGE OUTLINE

DGK0008A

VSSOP - 1.1 mm max height

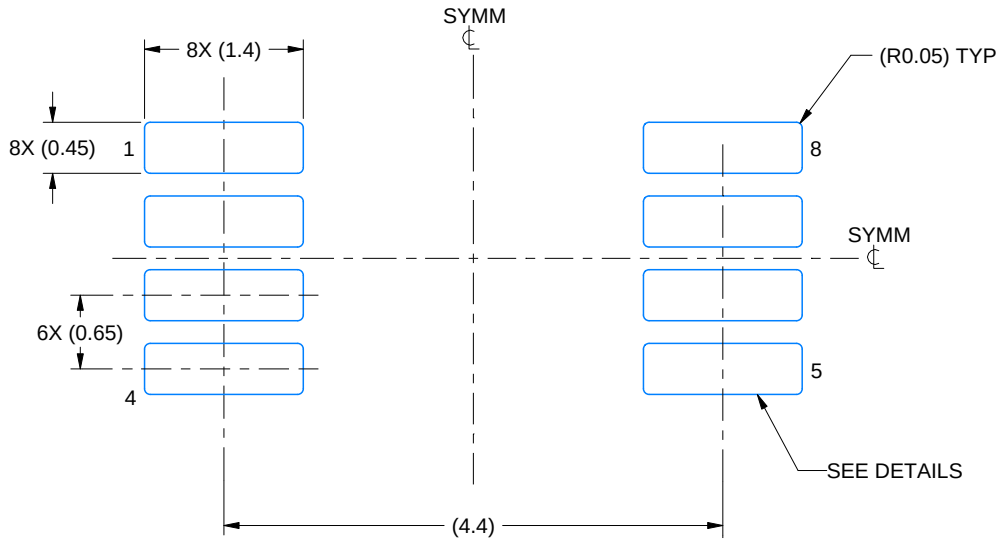
SMALL OUTLINE PACKAGE



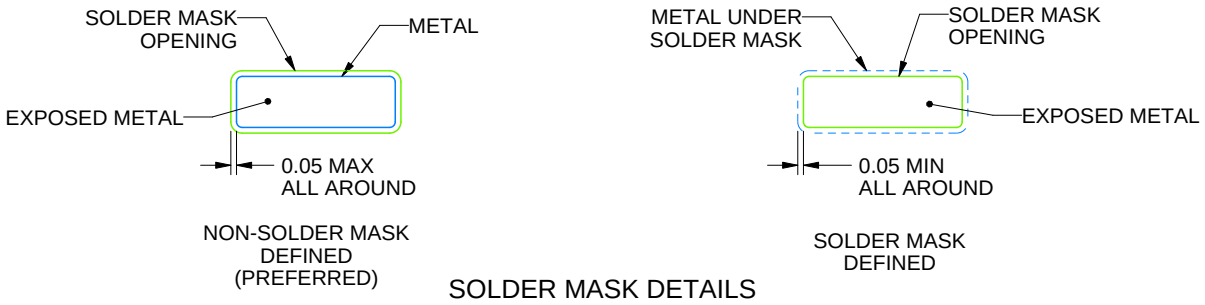
PowerPAD is a trademark of Texas Instruments.

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-187.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 15X



SOLDER MASK DETAILS

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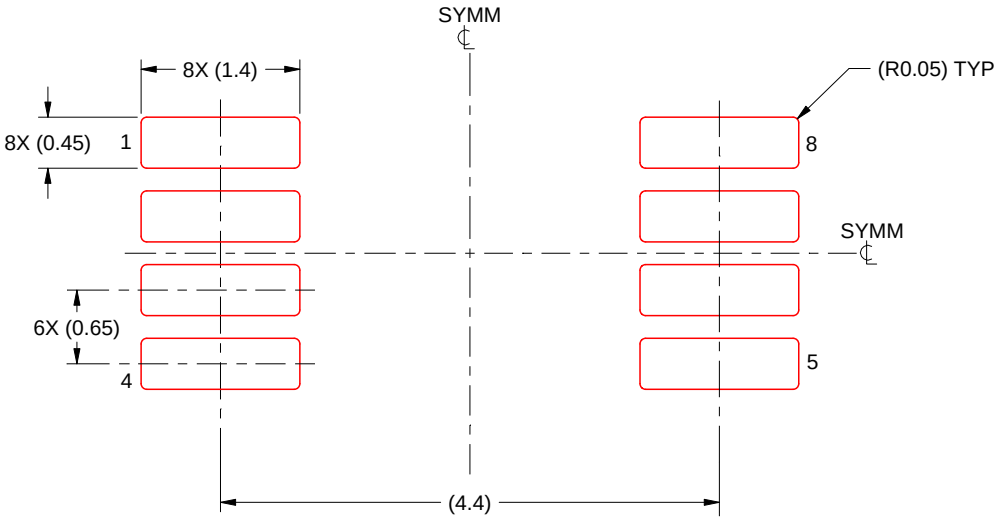
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.
9. Size of metal pad may vary due to creepage requirement.



SOLDER PASTE EXAMPLE
SCALE: 15X

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NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

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最后更新日期：2025 年 10 月